

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#2/a
Thompson
4/8/98

Serial No.: TBD

Art Unit: TBD

Filed: 12/20/97

Examiner: TBD

Inventor: Konecni, et al.

Docket: TI-22166

For: METHOD AND SYSTEM FOR SELECTIVELY COUPLING A CONDUCTIVE
MATERIAL TO A SURFACE OF A SEMICONDUCTOR DEVICE

Prior Serial No.: 60/033,728

Prior Filed: 12/20/96

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Date of Deposit: 12-11, 1997.

PRELIMINARY AMENDMENT

Honorable Assistant Commissioner of Patents

Washington, D.C. 20231

Dear Sir:

Prior to examination, please amend this application as follows and charge any necessary fees to deposit account 20-0668 of Texas Instruments Incorporated:

IN THE SPECIFICATION

Please amend page 1, after the "Title of the Invention" by inserting the following:

--This is a Non Provisional application filed under 35 USC 119(e) and claims priority of prior provisional, Serial No. 60/033,728 of inventor Konecni, et al, filed 12/20/96.--

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